

METHODS FOR ELECTROPLATING LARGE COPPER INTERCONNECTS

ABSTRACT OF THE DISCLOSURE

A method for forming conductive features in dielectric materials is disclosed which includes providing a dielectric layer and forming a release layer over the dielectric layer. Then a feature is defined into the each of the release layer and the dielectric layer and a conductive material is filled over the release layer and into the feature. The release layer is then removed where the removing serves to remove the conductive material from over the dielectric layer previously covered by the release layer.